



Material Content Data Sheet



Sales Product Name		BTS7012-1EPA		Issued		4. July 2019		
MA#		MA005285814						
Package		PG-TSDSO-14-22		Weight*		64.90 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.766	1.18	1.18	11806	11806
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		145	
	non noble metal	zinc	7440-66-6	0.038	0.06		581	
	non noble metal	iron	7439-89-6	0.754	1.16		11619	
wire	non noble metal	copper	7440-50-8	30.617	47.18	48.41	471762	484107
	non noble metal	copper	7440-50-8	0.495	0.76	0.76	7633	7633
	encapsulation	organic material	carbon black	1333-86-4	0.088	0.14		1362
encapsulation	plastics	epoxy resin	-	3.448	5.31		53125	
	inorganic material	silicondioxide	60676-86-0	25.932	39.96	45.41	399571	454058
leadfinish	non noble metal	tin	7440-31-5	1.642	2.53	2.53	25295	25295
plating	noble metal	silver	7440-22-4	0.816	1.26	1.26	12574	12574
glue	plastics	epoxy resin	-	0.051	0.08		792	
	noble metal	silver	7440-22-4	0.242	0.37	0.45	3735	4527
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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